

## BAF-726

*No Clean Tacky Paste Flux*



### Product Description

BAF-726 is a no-clean flux specially designed for CSP assembly and rework applications. BAF-726 can be transferred to the pad by pin-transfer or chip-dip process involving a rotating disc a doctor's blade for flux levelling. The operating-life is >16 hours (20-25°C and RH 45-65%) without much change in viscosity. BAF726 can also be dispensed or printed for BGA or SMD rework. The post-soldered residue is ultra low, benign and can left on the circuit. If desired, the residue can be removed with most commercial solvents and megasonic energy.

BAF-726 has been optimised to have an unbeatable list of benefits, some are:

- Mild flux chemistry – no-clean flux design.
- Zero Halogen (ROLO) flux system - no corrosion.
- Trouble-free dipping or pin transfer – no drying in the reservoir tray.
- High tack force – secures component in place prior to reflow.
- Fast wetting – smooth solder joint.
- Cosmetically clean appearance – ultra-low residue.
- Negligible interfacial void – high joint reliability.
- No-clean formulation – if desired, residue can be removed with standard cleaners with megasonic energy.

### Application

BAF-726 is great for general lead free and leaded applications and also rework applications of various electronic devices. It is ideally suited for applications such as pin transfer, ball dip process and stencil printing process.

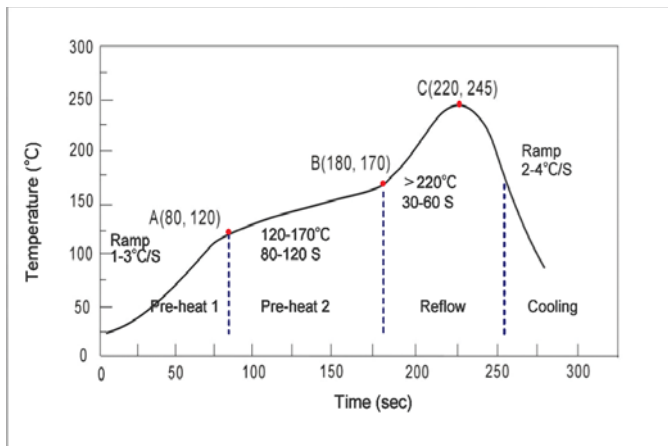
For a 0.2 x 0.2mm pad, ca 100µl of flux may be acceptable for good soldering. The chip should be pressed into the flux and make contact with the pad. These are intended for minimal risk of chip movement during reflow. For dipping or pin transfer, flux should cover 50-70% of the ball height.

### Specification (*Preliminary*)

Item	Result
Appearance	white color cream
Viscosity Brookfield HBDV-II Pro Cone & Plate Viscometer	150 - 3000 cp (5 rpm @ 25°C)
Density	0.85 g/cm <sup>3</sup>
Halide Content JIS Z 3197 8.1.4.2.1	No Detected
Copper Mirror Test IPC-TM-650 2.3.32 JIS Z 3197 8.4.2	Classified as "L", Pass
Copper Corrosion Test IPC-TM-650 2.6.15 JIS Z 3197 8.4.1	Pass
Flux Activity Classification IPC J-STD-004	ROLO
Surface Insulation Resistance (85°C, 85%RH, 168hrs) IPC-TM-650 2.6.3.3	> 1 x 10 <sup>8</sup> Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs) IPC-TM-650 2.6.14.1	Pass

## Recommended Reflow Profile

BAF-726 can be used to reflow SAC305 solder spheres in nitrogen (N<sub>2</sub>) with the following profile:



## Residue Removal

Post-soldered residue of BAF-726 can be removed by most commercial solvent.

## Storage, Handling and Shelf Life

Paste flux has to be thawed to room temperature (~25°C) prior using to avoid condensation. Paste flux left on the stencil should not be put back into the container together with the unused paste flux. It is preferable not to re-use paste flux left on the stencil after printing. BAF-726 can be stored at 20-25°C and used within 6 months.

## Health and Safety

Do not handle the paste flux with your bare hand. Use proper tool when handling the paste flux. If the paste flux touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet. paste touches the skin, wash thoroughly with soap and water. For more information, please refer to Material Safety Data Sheet.

## Packaging

BAF-726 paste flux is available in 10gm and 30gm luer-lok syringes. For other packaging requirements, please contact Asahi sales department.

### DISCLAIMER OF LIABILITY

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